

機密文件

REV.	MODIFICATION	DRAWN	APPROVED
N	EN110307	王德友	LEO

NOTES :

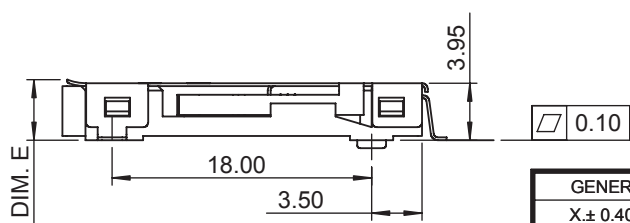
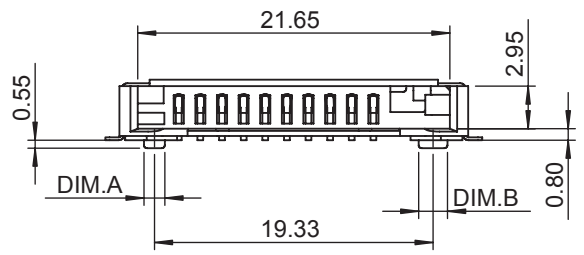
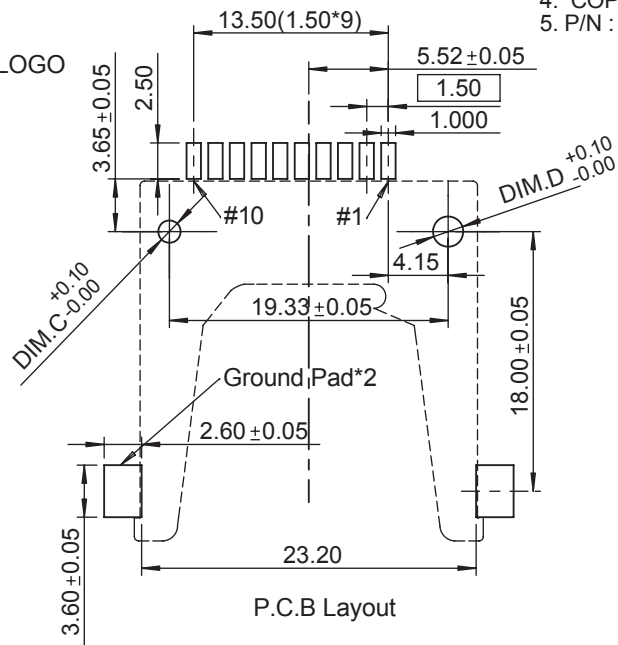
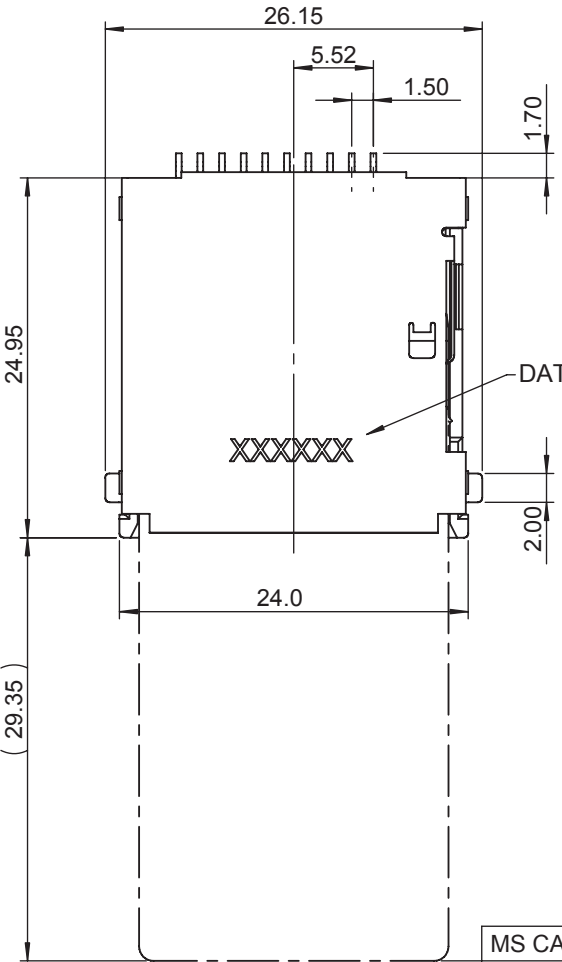
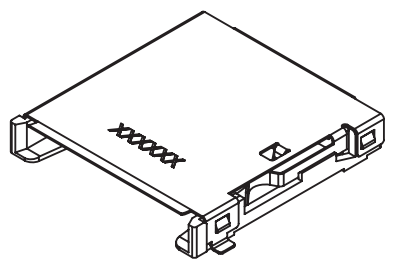
- MATERIAL :  
INSULATOR : HIGH TEMPERATURE THERMOPLASTIC,UL 94V-0 ,COLOR : BLACK  
CONTACT : COPPER ALLOY
- CONTACT AREA PLATING : GOLD OVER Ni  
SOLDER AREA: TIN/LEAD OR UNLEAD PLATING
- THIS PARTS SHOULD NOT CONTAIN ANY SUBSTANCES WHICH ARE SPECIFIED IN KQA-2V03
- COPLANARITY MUST BE WITHIN 0.10
- P/N : MSC010- X 0 - 1 X X X

LEAD IN (DIM. E):  
0 - WITH LEAD IN, DIM. E=4.20mm  
1 - W/O LEAD IN, DIM. E=3.95mm

SEE THE TABLE 1

DATE CODE:  
0 - With Date Code & LOGO  
1 - W/O Date Code & LOGO

PLATING:  
0 - GOLD FLASH  
2 - 10u"GOLD  
UNLEAD PLATING:  
A - GOLD FLASH  
C - 10u"GOLD



		Memory Stick PRO		Memory Stick
NO.	Pin Name	Serial	Parallel	Serial
#1	VSS	Vss		
#2	BS	Protocol Bus State Signal		
#3	DATA1	Hi-Z	Data Signal 1	Vcc
#4	SDIO/DATA0	Data Signal	Data Signal 0	Data Signal
#5	DATA2	Hi-Z	Data Signal 2	Reserved
#6	INS	Stick insertion/extraction detect-terminal		
#7	DATA3	Hi-Z	Data Signal 3	Reserved
#8	SCLK	Protocol Clock Signal		
#9	VCC	Vcc		
#10	VSS	Vss		

TABLE 1

料號	DIM.A	DIM.B	DIM.C	DIM.D
MSC010-X0-1X0X	φ 1.45	φ 2.00	φ 1.55	φ 2.10
MSC010-X0-1X1X	φ 1.35	φ 1.35	φ 1.50	φ 1.50



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2. ALL RIGHTS RESERVED. PRODUCTS ARE COVERED BY PATENTS AND/OR PATENTS PENDING.

GENERAL TOLERANCE	
X ± 0.40	X ° ± 5°
.X ± 0.30	.X ° ± 2°
.XX ± 0.20	.XX ° ± 1°
.XXX ± 0.10	.XXX ° ± 0.5°

Wellco T&C Co., Ltd.  
TITLE: Memory Stick Connector Reverse type

CUSTOMER DRAWING		PART NO. MSC010-X0-1XXX	DWG NO. MSC010-02-N
APPROVAL	CHECKED	DRAWN	UNIT mm
SCALE NONE	SHEET 1 / 1	PROJ.	REV. N